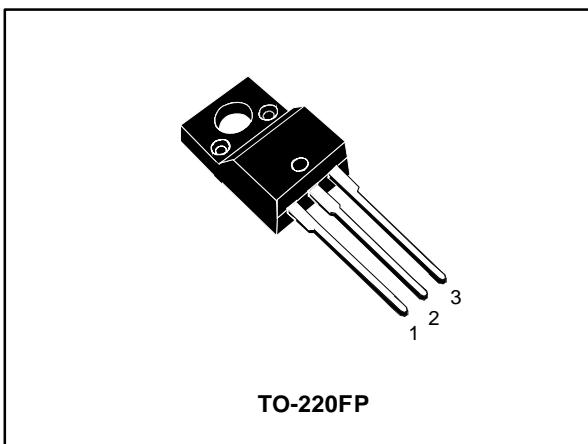
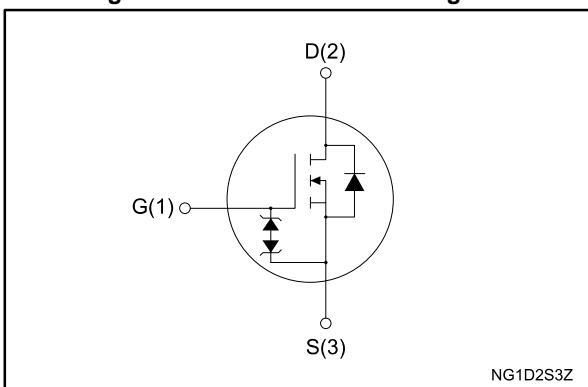


## N-channel 600 V, 0.13 Ω typ., 21 A MDmesh™ DM2 Power MOSFET in a TO-220FP package

Datasheet - production data



**Figure 1: Internal schematic diagram**



**Table 1: Device summary**

Order code	Marking	Package	Packing
STF28N60DM2	28N60DM2	TO-220FP	Tube

### Features

Order code	V <sub>DS</sub> @ T <sub>Jmax.</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>	P <sub>TOT</sub>
STF28N60DM2	650 V	0.16 Ω	21 A	30 W

- Fast-recovery body diode
- Extremely low gate charge and input capacitance
- Low on-resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

### Applications

- Switching applications

### Description

This high voltage N-channel Power MOSFET is part of the MDmesh™ DM2 fast recovery diode series. It offers very low recovery charge ( $Q_{rr}$ ) and time ( $t_{rr}$ ) combined with low  $R_{DS(on)}$ , rendering it suitable for the most demanding high efficiency converters and ideal for bridge topologies and ZVS phase-shift converters.

## Contents

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# 1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D$	Drain current (continuous) at $T_{case} = 25^\circ\text{C}$	21	A
	Drain current (continuous) at $T_{case} = 100^\circ\text{C}$	14	
$I_{DM}^{(1)}$	Drain current (pulsed)	84	A
$P_{TOT}$	Total dissipation at $T_{case} = 25^\circ\text{C}$	30	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	50	V/ns
$dv/dt^{(3)}$	MOSFET dv/dt ruggedness	50	
$V_{ISO}^{(4)}$	Insulation withstand voltage (RMS) from all three leads to external heat sink	2.5	kV
$T_{stg}$	Storage temperature	-55 to 150	$^\circ\text{C}$
$T_j$	Operating junction temperature		

**Notes:**

(1) Pulse width is limited by safe operating area.

(2)  $I_{SD} \leq 21$  A,  $dI/dt=900$  A/ $\mu\text{s}$ ;  $V_{DS}$  peak <  $V_{(BR)DSS}$ ,  $V_{DD} = 400$  V(3)  $V_{DS} \leq 480$  V.(4) $t = 1$  s;  $T_C = 25^\circ\text{C}$ 

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	4.2	$^\circ\text{C/W}$
$R_{thj-amb}$	Thermal resistance junction-ambient	62.5	

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
$I_{AR}^{(1)}$	Avalanche current, repetitive or not repetitive	4	A
$E_{AS}^{(2)}$	Single pulse avalanche energy	350	mJ

**Notes:**(1) pulse width limited by  $T_{jmax}$ (2) starting  $T_j = 25^\circ\text{C}$ ,  $I_D = I_{AR}$ ,  $V_{DD} = 50$  V.

## 2 Electrical characteristics

( $T_{case} = 25^\circ C$  unless otherwise specified)

**Table 5: Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0 V, I_D = 1 mA$	600			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0 V, V_{DS} = 600 V$			1	$\mu A$
		$V_{GS} = 0 V, V_{DS} = 600 V, T_{case} = 125^\circ C$			100	
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0 V, V_{GS} = \pm 25 V$			$\pm 10$	$\mu A$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	3	4	5	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10 V, I_D = 10.5 A$		0.13	0.16	$\Omega$

**Table 6: Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100 V, f = 1 MHz, V_{GS} = 0 V$	-	1500	-	$pF$
$C_{oss}$	Output capacitance		-	70	-	
$C_{rss}$	Reverse transfer capacitance		-	1.6	-	
$C_{oss\ eq.\ (1)}$	Equivalent output capacitance	$V_{DS} = 0$ to $480 V, V_{GS} = 0 V$	-	134	-	$pF$
$R_G$	Intrinsic gate resistance	$f = 1 MHz, I_D = 0 A$	-	4.6	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 480 V, I_D = 21 A, V_{GS} = 10 V$ (see <i>Figure 15: "Test circuit for gate charge behavior"</i> )	-	34	-	$nC$
$Q_{gs}$	Gate-source charge		-	8	-	
$Q_{gd}$	Gate-drain charge		-	18.5	-	

### Notes:

(1)  $C_{oss\ eq.}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 7: Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300 V, I_D = 10.5 A, R_G = 4.7 \Omega, V_{GS} = 10 V$ (see <i>Figure 14: "Test circuit for resistive load switching times"</i> and <i>Figure 19: "Switching time waveform"</i> )	-	16	-	$ns$
$t_r$	Rise time		-	7.3	-	
$t_{d(off)}$	Turn-off delay time		-	53	-	
$t_f$	Fall time		-	9.3	-	

Table 8: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}^{(1)}$	Source-drain current		-		21	A
$I_{SDM}^{(2)}$	Source-drain current (pulsed)		-		84	A
$V_{SD}^{(3)}$	Forward on voltage	$V_{GS} = 0 \text{ V}$ , $I_{SD} = 21 \text{ A}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 21 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ , $V_{DD} = 60 \text{ V}$ (see <a href="#">Figure 16: "Test circuit for inductive load switching and diode recovery times"</a> )	-	140		ns
$Q_{rr}$	Reverse recovery charge		-	0.5		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	7.4		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 21 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ , $V_{DD} = 60 \text{ V}$ , $T_j = 150 \text{ }^\circ\text{C}$ (see <a href="#">Figure 16: "Test circuit for inductive load switching and diode recovery times"</a> )	-	309		ns
$Q_{rr}$	Reverse recovery charge		-	2.6		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	16.8		A

**Notes:**

(1) Limited by maximum junction temperature.

(2) Pulse width is limited by safe operating area.

(3) Pulse test: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

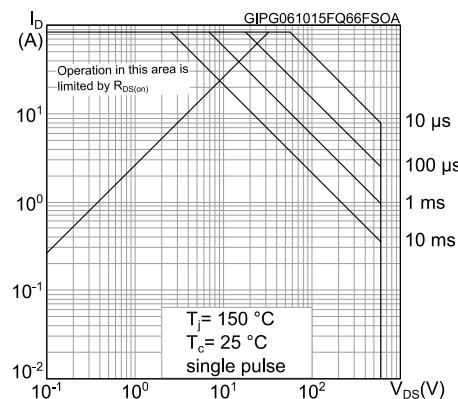
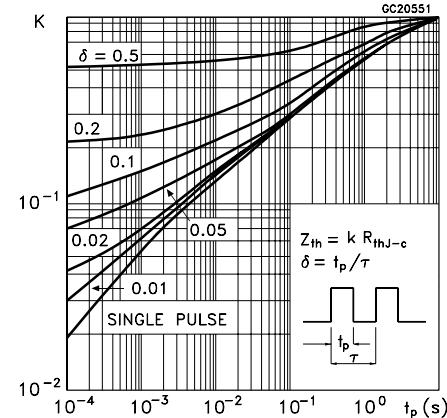
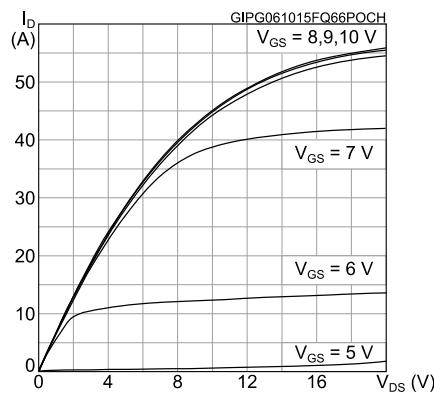
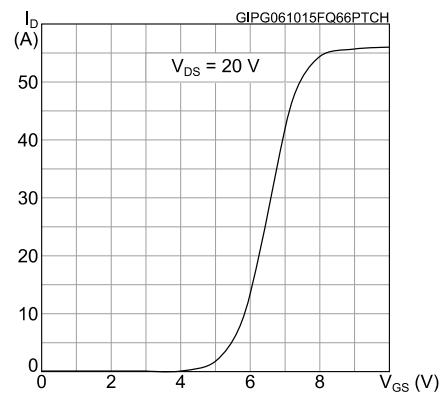
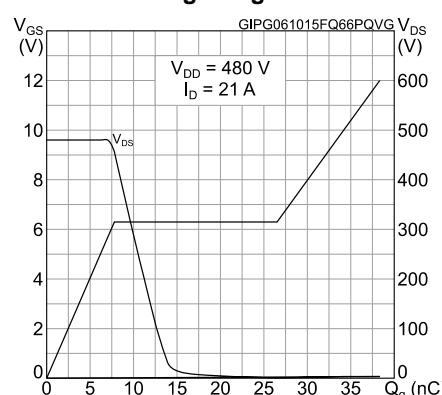
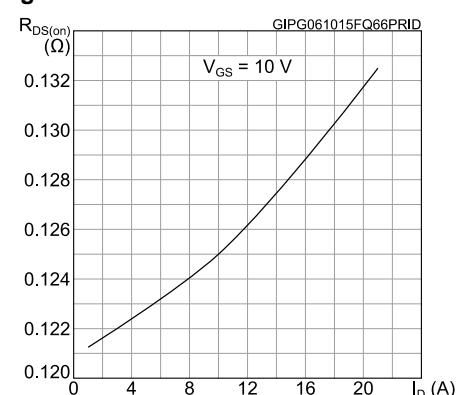
Table 9: Gate-source Zener diode

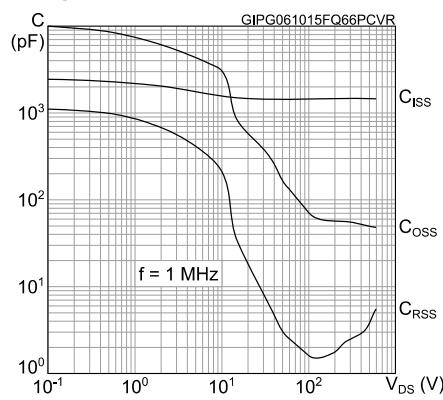
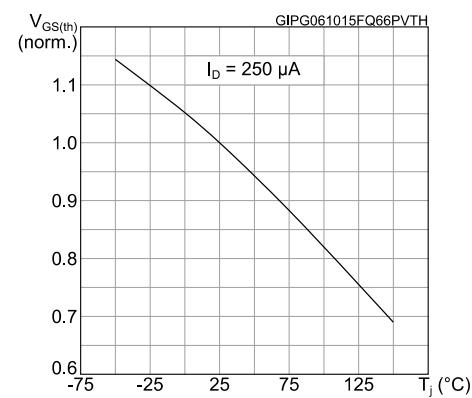
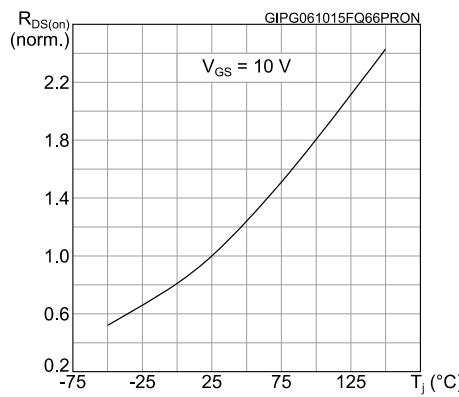
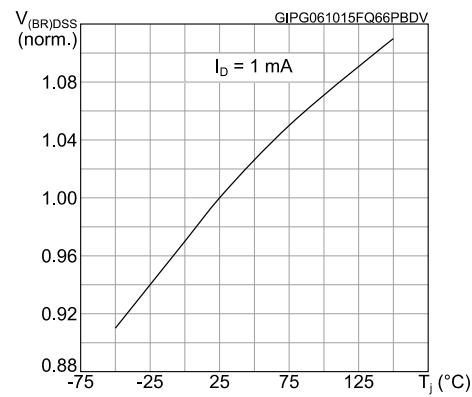
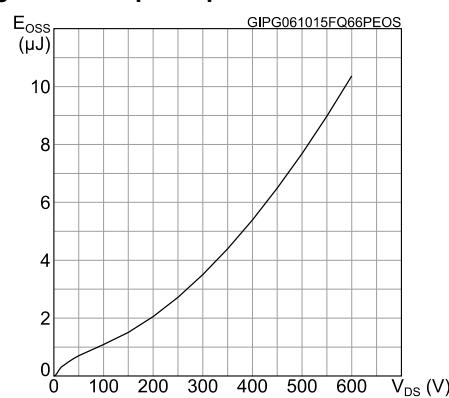
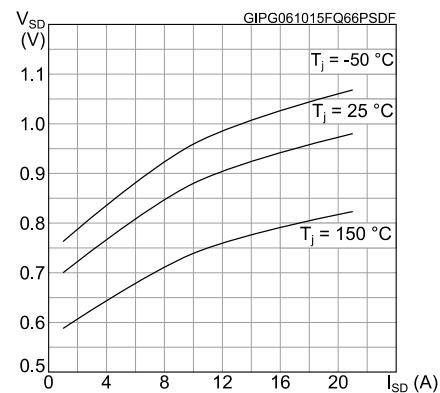
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	$I_{GS} = \pm 250 \mu\text{A}$ , $I_D = 0 \text{ A}$	$\pm 30$	-	-	V

The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.

## 2.1

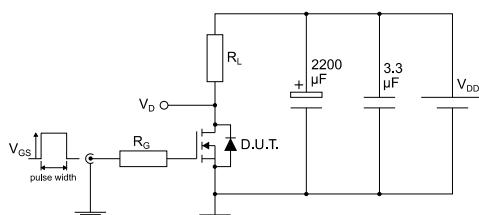
## Electrical characteristics (curves)

**Figure 2: Safe operating area****Figure 3: Thermal impedance****Figure 4: Output characteristics****Figure 5: Transfer characteristics****Figure 6: Gate charge vs gate-source voltage****Figure 7: Static drain-source on-resistance**

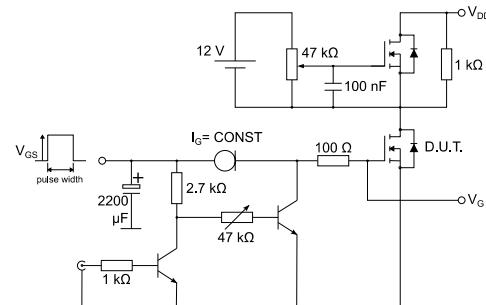
**Figure 8: Capacitance variations****Figure 9: Normalized gate threshold voltage vs temperature****Figure 10: Normalized on-resistance vs temperature****Figure 11: Normalized V(BR)DSS vs temperature****Figure 12: Output capacitance stored energy****Figure 13: Source-drain diode forward characteristics**

### 3 Test circuits

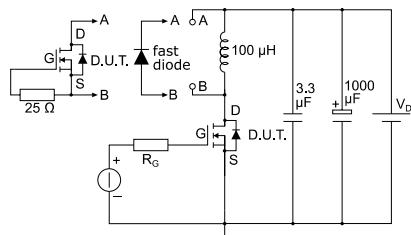
**Figure 14: Test circuit for resistive load switching times**



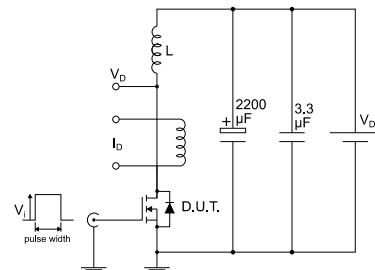
**Figure 15: Test circuit for gate charge behavior**



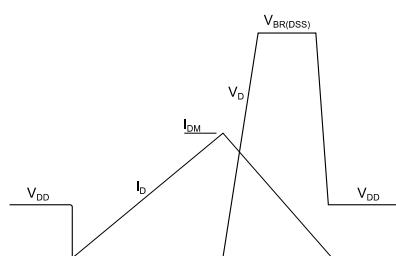
**Figure 16: Test circuit for inductive load switching and diode recovery times**



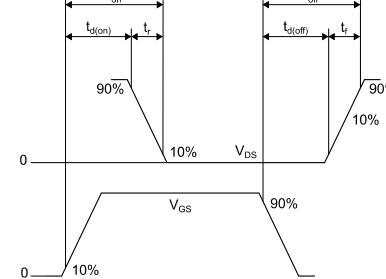
**Figure 17: Unclamped inductive load test circuit**



**Figure 18: Unclamped inductive waveform**



**Figure 19: Switching time waveform**



## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com).  
ECOPACK® is an ST trademark.

### 4.1 TO-220FP package information

Figure 20: TO-220FP package outline

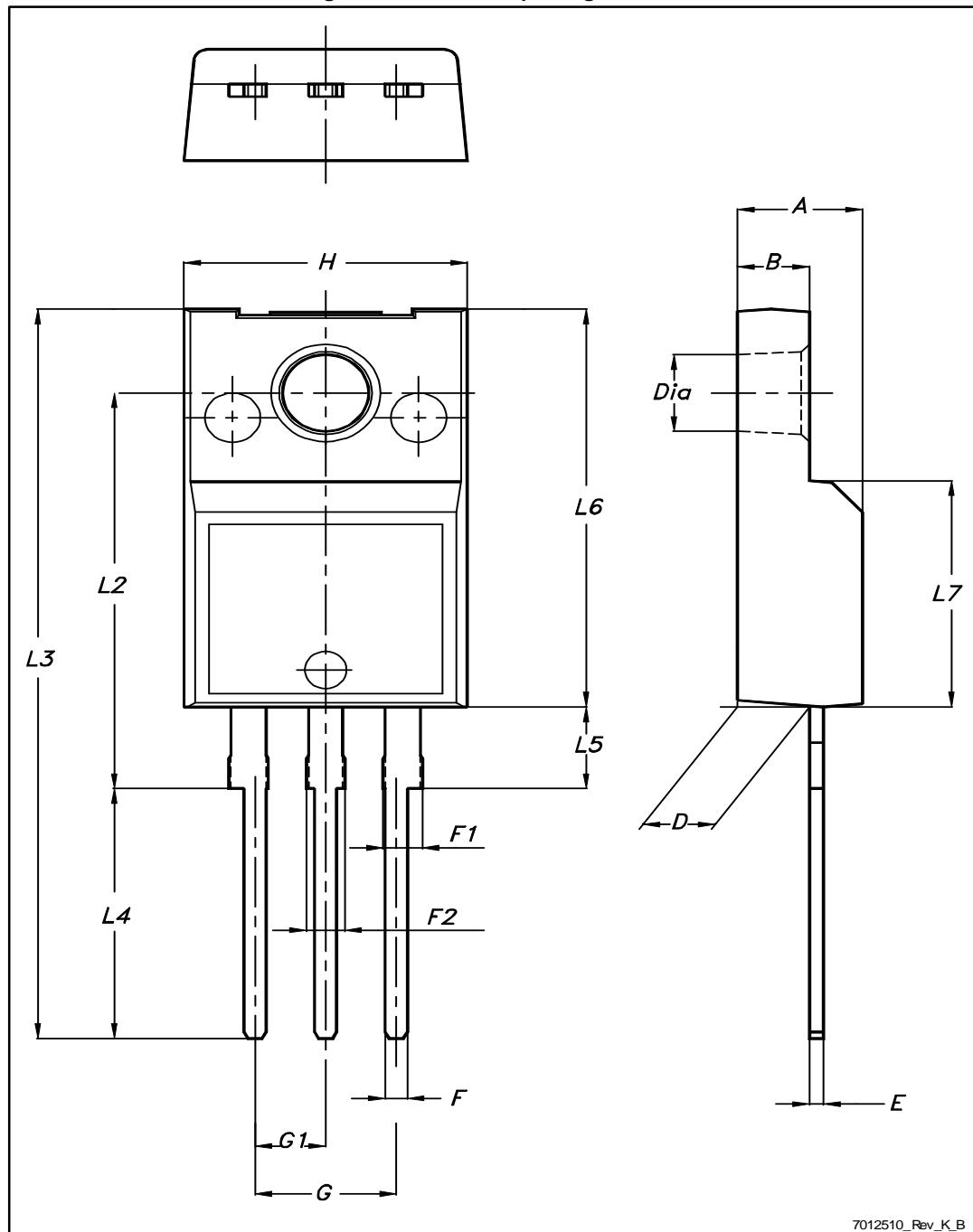


Table 10: TO-220FP package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

## 5 Revision history

Table 11: Document revision history

Date	Revision	Changes
04-Sep-2014	1	First release.
09-Oct-2015	2	<p>Text and formatting changes throughout document</p> <p>On cover page:</p> <ul style="list-style-type: none"><li>- updated title and Features table</li></ul> <p>In section Electrical ratings:</p> <ul style="list-style-type: none"><li>- updated all table data</li></ul> <p>In section Electrical characteristics:</p> <ul style="list-style-type: none"><li>- updated all table data</li><li>- renamed table Static (was On /off states)</li><li>- added table Gate-source Zener diode</li></ul> <p>Added section Electrical characteristics (curves)</p> <p>Updated and renamed section Package mechanical data (was Package information)</p> <p>Datasheet promoted from preliminary to production data</p>

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